

# EE 330

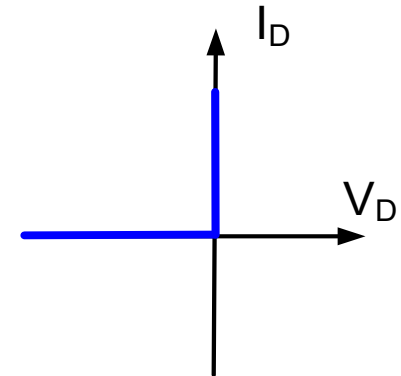
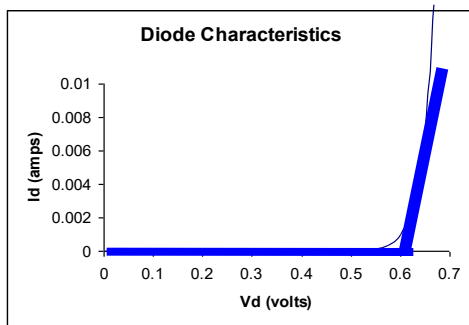
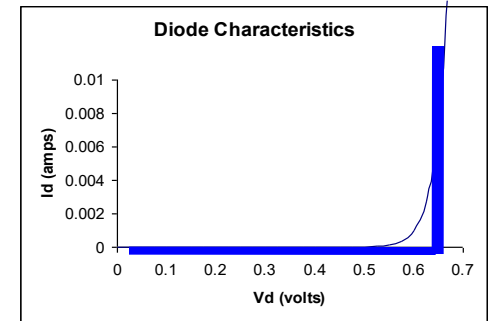
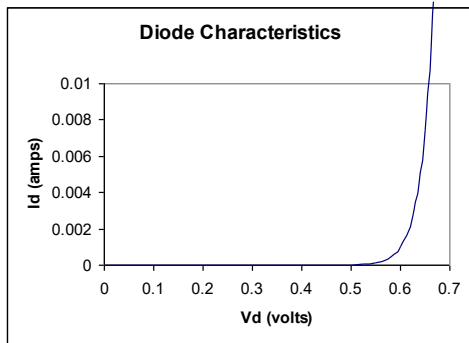
## Lecture 16

### Devices in Semiconductor Processes

- MOSFETs

# Fall 2025 Exam Schedule

Exam 1	Friday	Sept 26
Exam 2	Friday	October 24
Exam 3	Friday	Nov 21
Final Exam	Monday	Dec 15 12:00 - 2:00 PM



Which model should be used?

The simplest model that will give acceptable results in the analysis of a circuit

# Analysis of Nonlinear Circuits

(Circuits with one or more nonlinear devices)

What analysis tools or methods can be used?

KCL ?

Nodal Analysis ?

KVL?

Mesh Analysis ?

~~Superposition?~~

Two-Port Subcircuits ?

~~Voltage Divider ?~~

~~Passing Current ?~~

~~Current Divider?~~

~~Blocking Current ?~~

~~Thevenin and Norton Equivalent Circuits?~~

- How are piecewise models accommodated?
- Will address the issue of how to rigorously analyze nonlinear circuits with piecewise models later

# Use of Piecewise Models for Nonlinear Devices when Analyzing Electronic Circuits

Process:

1. Guess state of the device
2. Analyze circuit
3. Verify State
4. Repeat steps 1 to 3 if verification fails
5. Verify model (if necessary)

Observations:

- Analysis generally simplified dramatically (particularly if piecewise model is linear)
- Approach applicable to wide variety of nonlinear devices
- Closed-form solutions give insight into performance of circuit
- Usually much faster than solving the nonlinear circuit directly
- Wrong guesses in the state of the device do not compromise solution (verification will fail)
- Helps to guess right the first time
- Detailed model is often not necessary with most nonlinear devices
- Particularly useful if piecewise model is PWL (but not necessary)
- For practical circuits, the simplified approach usually applies

**Key Concept For Analyzing Circuits with Nonlinear Devices**

# Use of Piecewise Models for Nonlinear Devices when Analyzing Electronic Circuits

## Single Nonlinear Device

Process:

1. Guess state of the device
2. Analyze circuit
3. Verify State
4. Repeat steps 1 to 3 if verification fails
5. Verify model (if necessary)

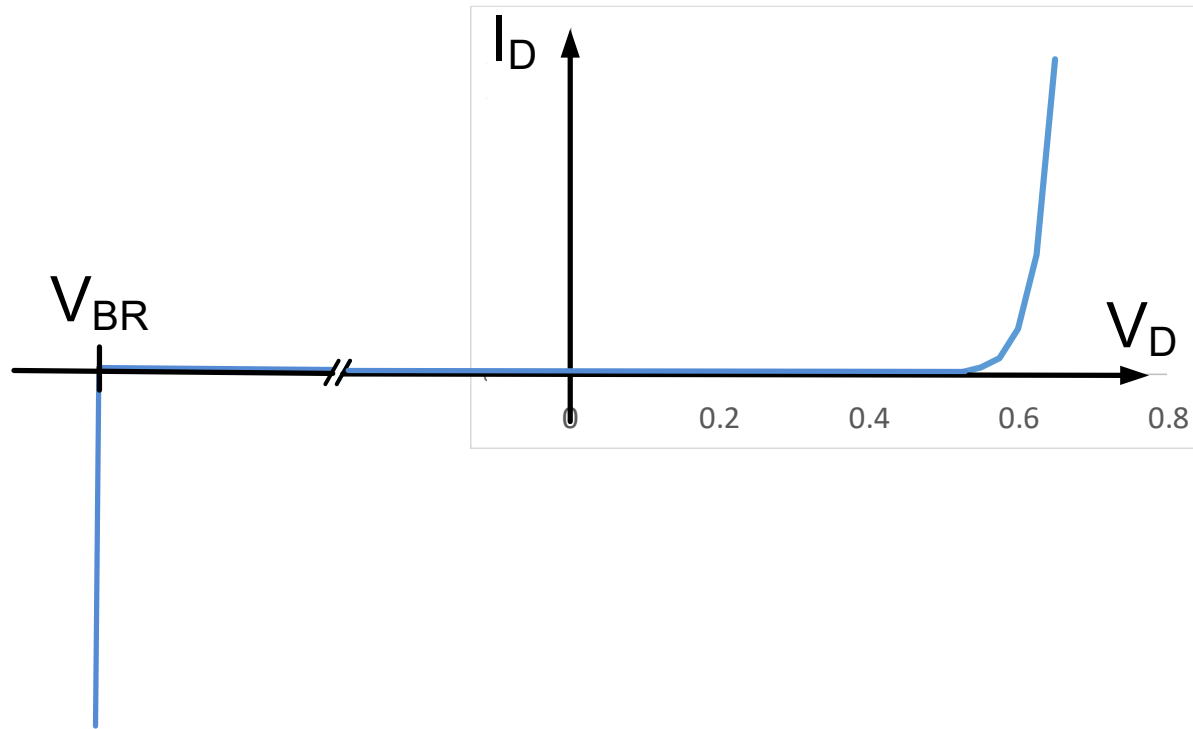
## Multiple Nonlinear Devices

Process:

1. Guess state of each device (may be multiple combinations)
2. Analyze circuit
3. Verify State
4. Repeat steps 1 to 3 if verification fails
5. Verify models (if necessary)

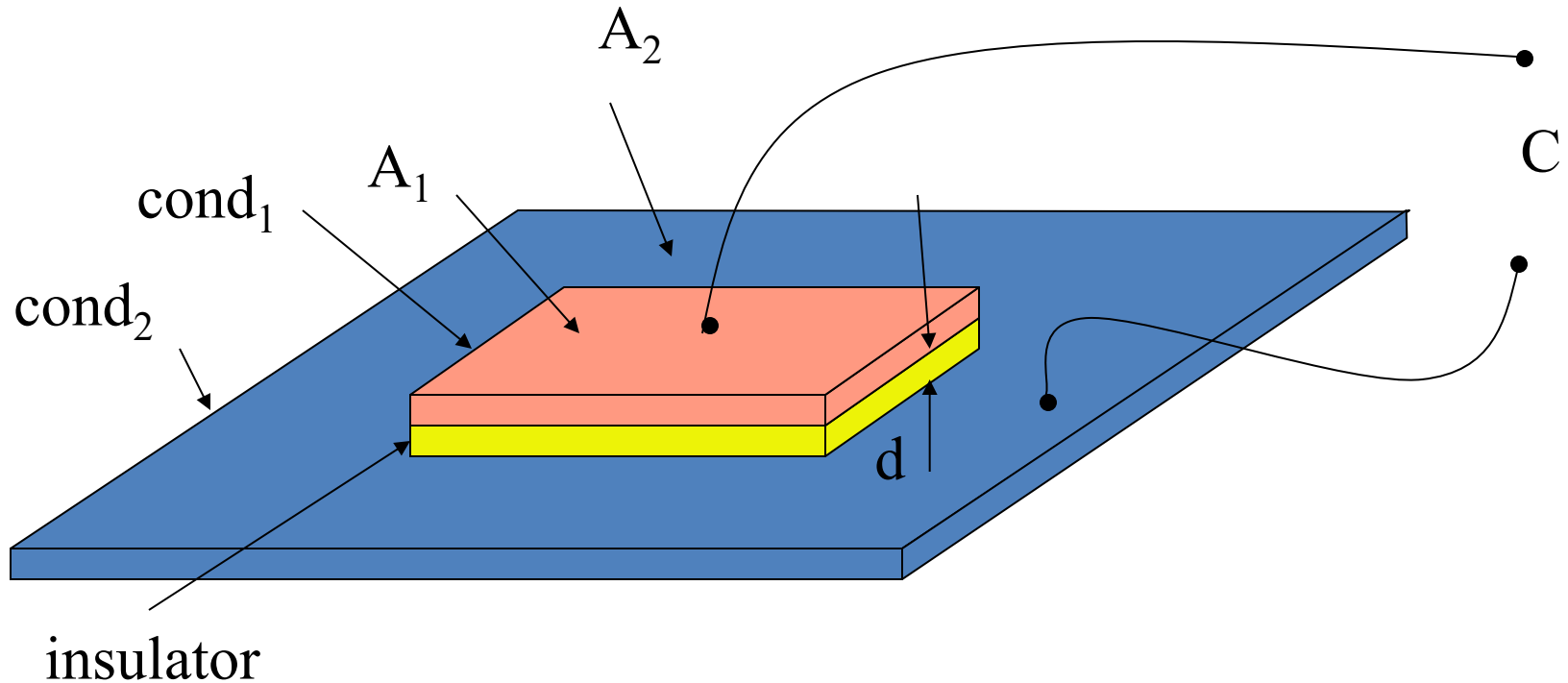
Analytical solutions of circuits with multiple nonlinear devices are often impossible to obtain if detailed non-piecewise nonlinear models are used

# Diode Breakdown



- Diodes will “break down” if a large reverse bias is applied
- Unless current is limited, reverse breakdown is destructive
- Breakdown is very sharp
- For many signal diodes,  $V_{BR}$  is in the -100V to -1000V range
- Relatively easy to design circuits so that with correct diodes, breakdown will not occur
- Zener diodes have a relatively small breakdown and current is intentionally limited to use this breakdown to build voltage references

# Parallel Plate Capacitors



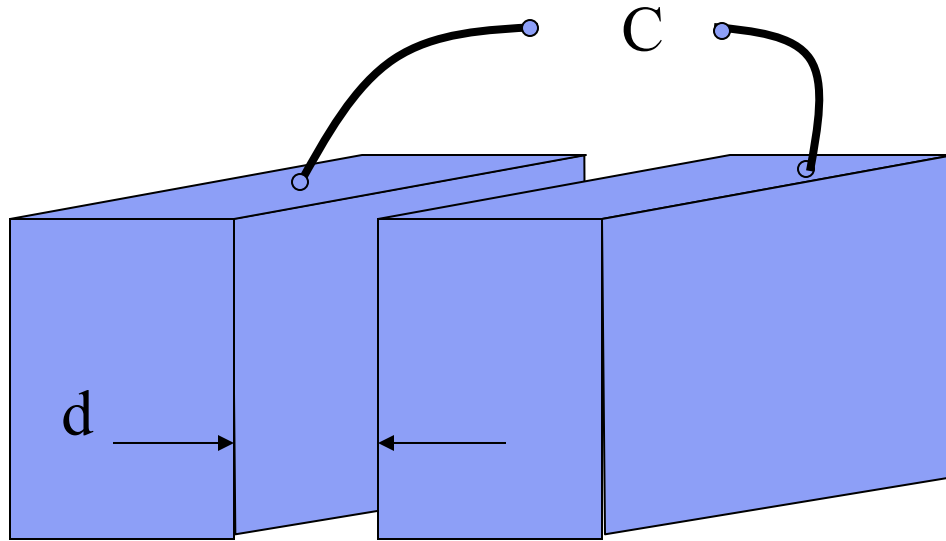
$A$  = area of intersection of  $A_1$  &  $A_2$

One (top) plate **intentionally** sized smaller to determine  $C$

$$C = \frac{\epsilon A}{d}$$



# Fringe Capacitors



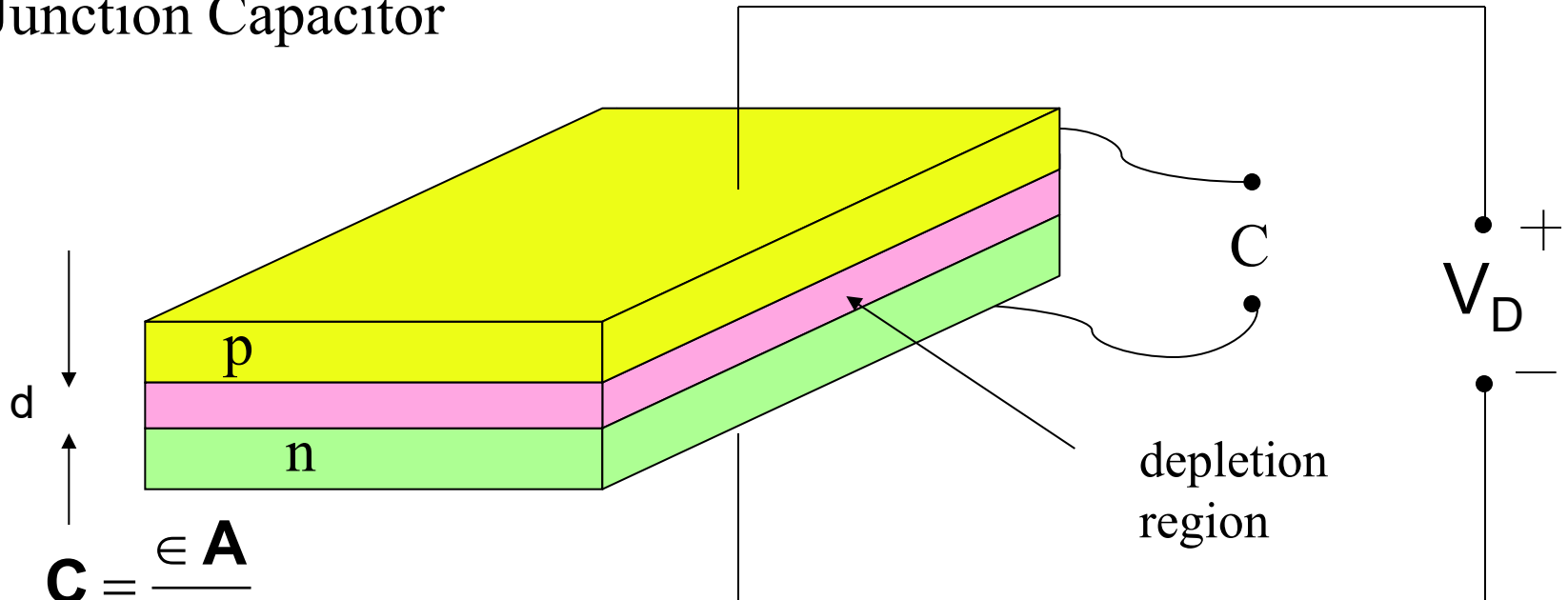
$$C = \frac{\epsilon A}{d}$$

A is the area where the two plates are parallel

**Only a single layer is needed to make fringe capacitors**

# Capacitance

## Junction Capacitor



$$C = \frac{\epsilon A}{d}$$

$\epsilon$  is dielectric constant

$$C = \frac{C_{j0} A}{\left(1 - \frac{V_D}{\phi_B}\right)^n} \quad \text{for } V_{FB} < \frac{\phi_B}{2}$$

Note:  $d$  is voltage dependent

-capacitance is voltage dependent

-usually parasitic caps

-varicaps or varactor diodes exploit voltage dep. of  $C$

$C_{j0}$  is the zero-bias junction capacitance density

Model parameters  $\{C_{j0}, n, \phi_B\}$     Design parameters  $\{A\}$

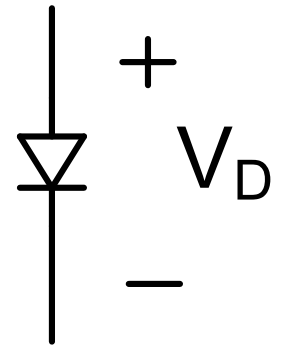
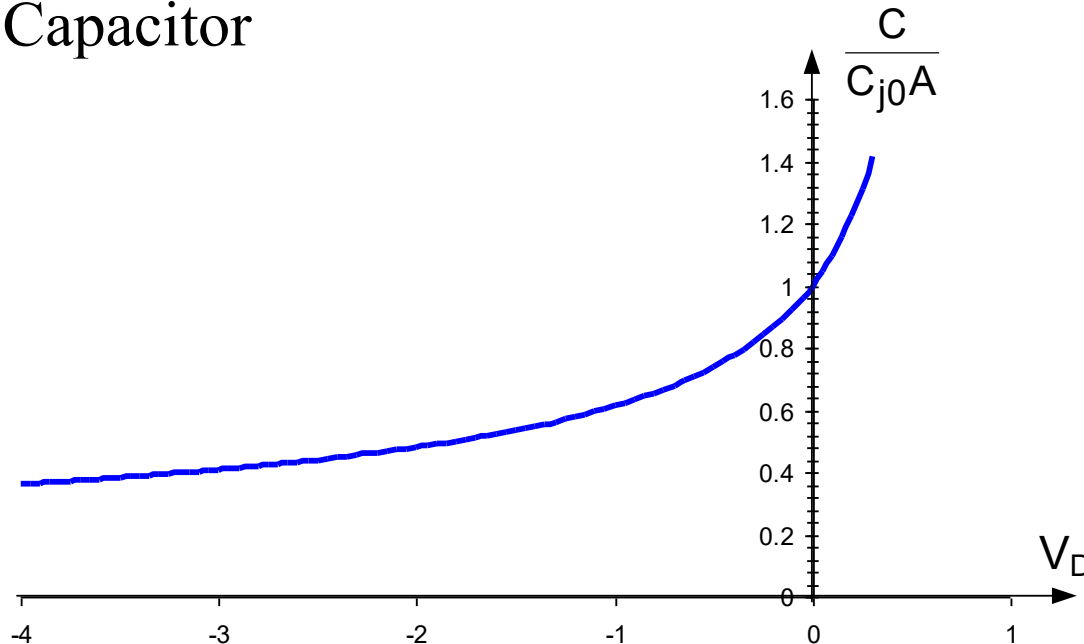
$$\phi_B \cong 0.6V$$

$$n \simeq 0.5$$

$$C_{j0} \text{ highly process dependent around } 500\text{aF}/\mu\text{m}^2$$

# Capacitance

## Junction Capacitor



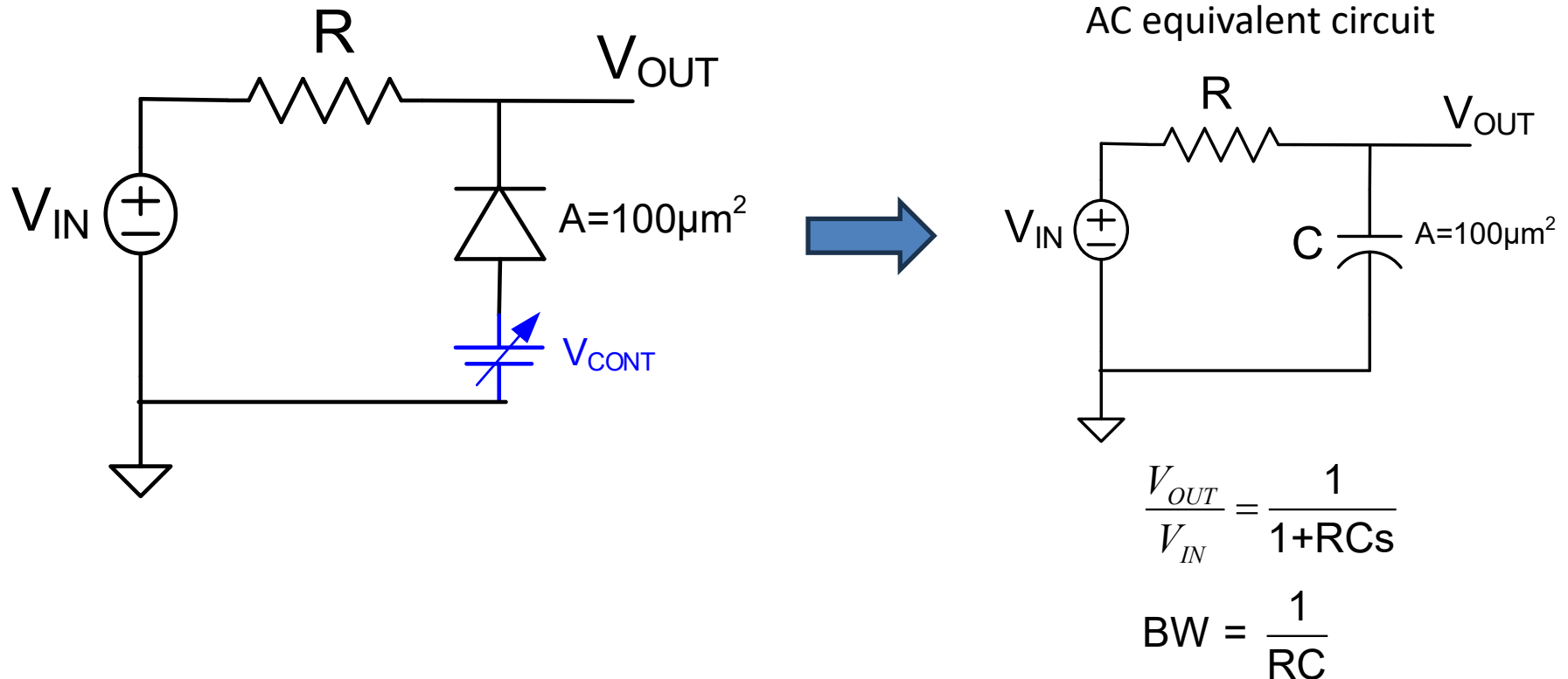
$$C = \frac{C_{j0}A}{\left(1 - \frac{V_D}{\phi_B}\right)^n} \quad \text{for } V_{FB} < \frac{\phi_B}{2}$$

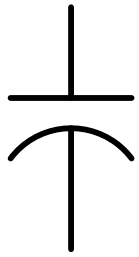
Voltage dependence is substantial

$$\phi_B \cong 0.6V \quad n \cong 0.5$$

## Example:

Determine the 3dB frequency of the lowpass filter shown if  $V_{\text{CONT}}=0\text{V}$  and if  $V_{\text{CONT}}=-2\text{V}$ . Assume  $R=10\text{M}$ , the diode junction area is  $100\mu\text{m}^2$ , and the diode is a p+:n-well diode in the process attached.





$$C = \frac{C_{jo}A}{\left(1 - \frac{V_D}{\phi_B}\right)^n}$$

$$\text{for } V_{FB} < \frac{\phi_B}{2}$$

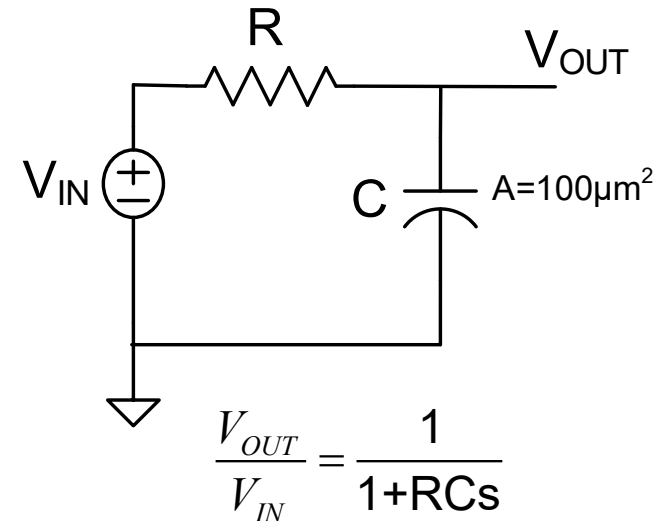
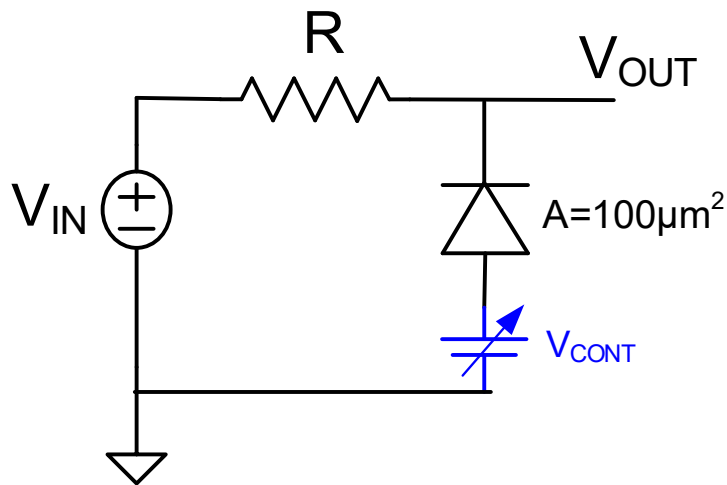
With  $V_D=0$   $C_1 = 37 \text{ aF } \mu\text{m}^{-2} \times 100 \mu\text{m}^2 = 3.7 \text{ fF}$

With  $V_D=-2\text{V}$   $C_2 = \frac{C_{jo}A}{\left(1 - \frac{V_D}{\phi_B}\right)^n} = \frac{3.7 \text{ fF}}{\left(1 + \frac{2\text{V}}{0.6\text{V}}\right)^{0.5}} = 1.78 \text{ fF}$

CAPACITANCE PARAMETERS	N+	P+	POLY	POLY2	M1	M2	M3	N_W	UNITS
Area ( <u>substrate</u> )	<u>425</u>	<u>731</u>	84		27	12	7	<u>37</u>	<u>aF/um^2</u>
Area ( <u>N+active</u> )			2434		35	16	11		<u>aF/um^2</u>
Area ( <u>P+active</u> )			2335						<u>aF/um^2</u>
Area ( <u>poly</u> )				938	56	15	9		<u>aF/um^2</u>
Area ( <u>poly2</u> )					49				<u>aF/um^2</u>
Area ( <u>metall1</u> )						31	13		<u>aF/um^2</u>
Area ( <u>metal2</u> )							35		<u>aF/um^2</u>
Fringe ( <u>substrate</u> )	<u>344</u>	<u>238</u>			49	33	23		<u>aF/um</u>
Fringe ( <u>poly</u> )					59	38	28		<u>aF/um</u>
Fringe ( <u>metall1</u> )						51	34		<u>aF/um</u>
Fringe ( <u>metal2</u> )							52		<u>aF/um</u>
Overlap ( <u>N+active</u> )			232						<u>aF/um</u>
Overlap ( <u>P+active</u> )			312						<u>aF/um</u>

# Example:

Determine the 3dB frequency of the lowpass filter shown if  $V_{\text{CONT}}=0\text{V}$  and if  $V_{\text{CONT}}=-2\text{V}$ . Assume  $R=10\text{M}$ , the diode junction area is  $100\mu\text{m}^2$ , and the diode is a p+:n-well diode in the process attached.



$$C_1 = 3.7\text{fF} \quad C_2 = 1.78\text{fF}$$

$$BW = \frac{1}{RC}$$

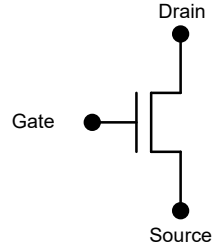
$$BW_1 = \frac{1}{RC_1} = \frac{1}{10\text{M} \cdot 3.7\text{fF}} = 27\text{M rad/sec} = 4.3\text{MHz}$$

$$BW_2 = \frac{1}{RC_2} = \frac{1}{10\text{M} \cdot 1.78\text{fF}} = 56\text{M rad/sec} = 8.9\text{MHz}$$

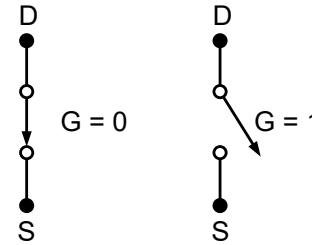
# Basic Devices and Device Models

- Resistor
- Diode
- Capacitor
- MOSFET
- BJT

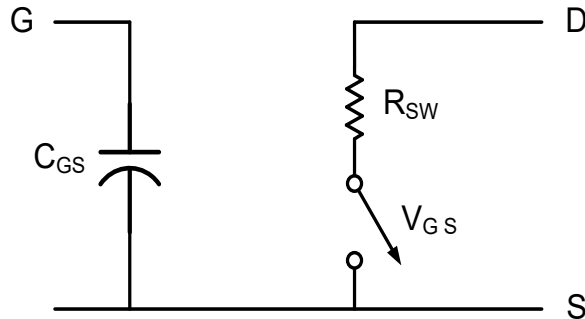
# Summary of Existing Models (for n-channel)



## 1. Switch-Level model



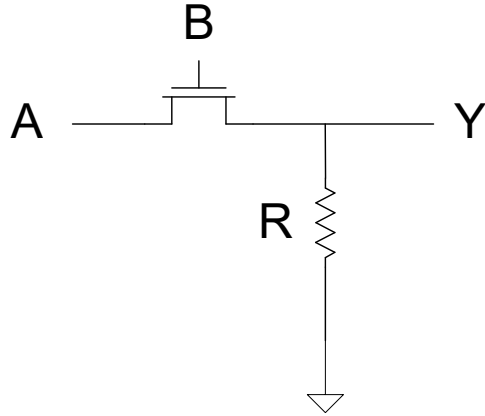
## 2. Improved switch-level model



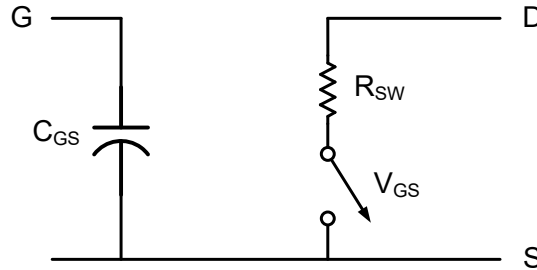
*Switch closed for  $|V_{GS}| = \text{large}$   
Switch open for  $|V_{GS}| = \text{small}$*



# Limitations of Existing MOSFET Models



What is Y when  $A=B=V_{DD}$

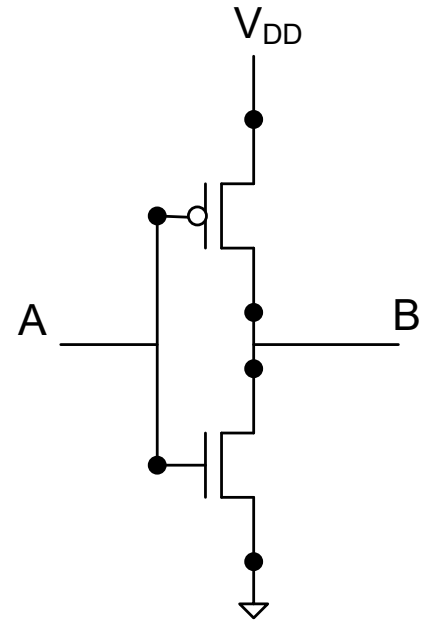


*For minimum-sized devices in a 0.5u process with  $V_{DD}=5V$*

$$C_{GS} \cong 1.5\text{fF}$$

$$R_{sw} \cong \left. \begin{array}{l} 2\text{K}\Omega \text{ n-channel} \\ 6\text{K}\Omega \text{ p-channel} \end{array} \right\}$$

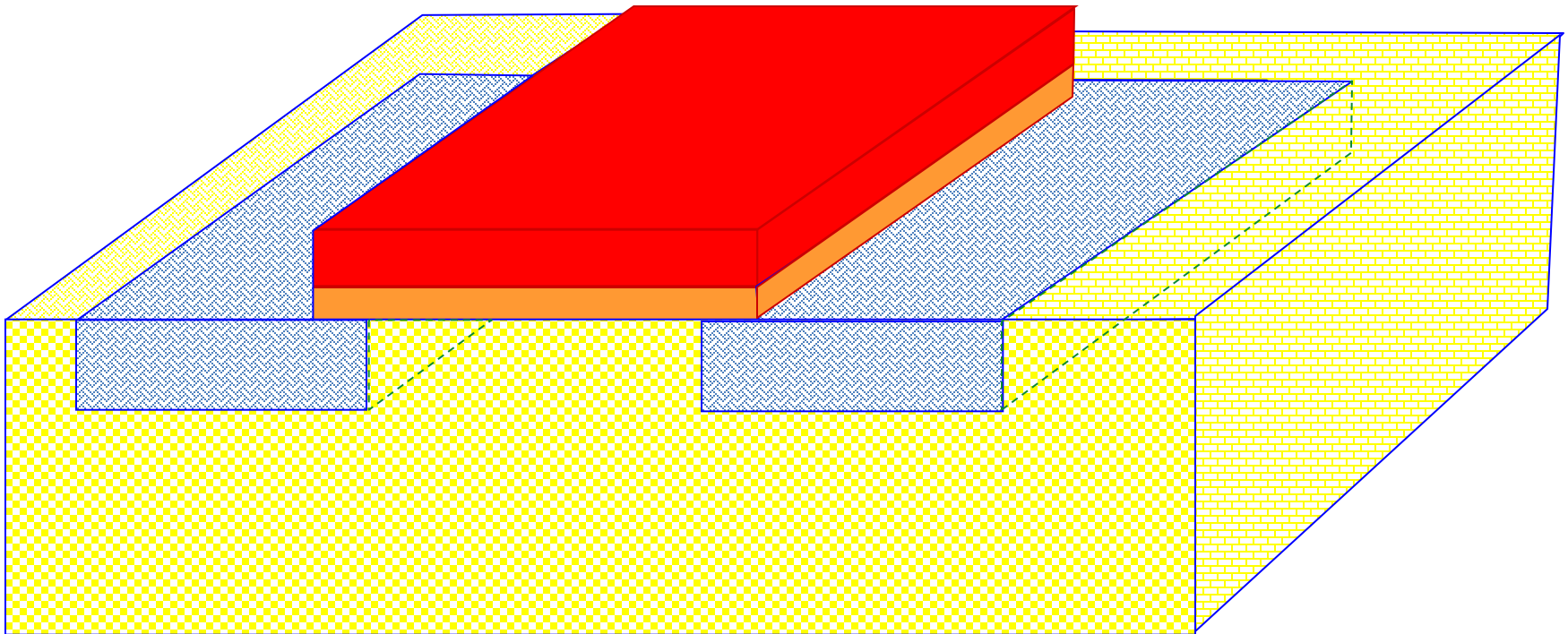
What is  $R_{sw}$  if MOSFET is not minimum sized?



What is power dissipation if A is stuck at an intermediate voltage?

**Better Model of MOSFET is Needed!**

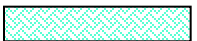
# n-Channel MOSFET



Poly



Gate oxide

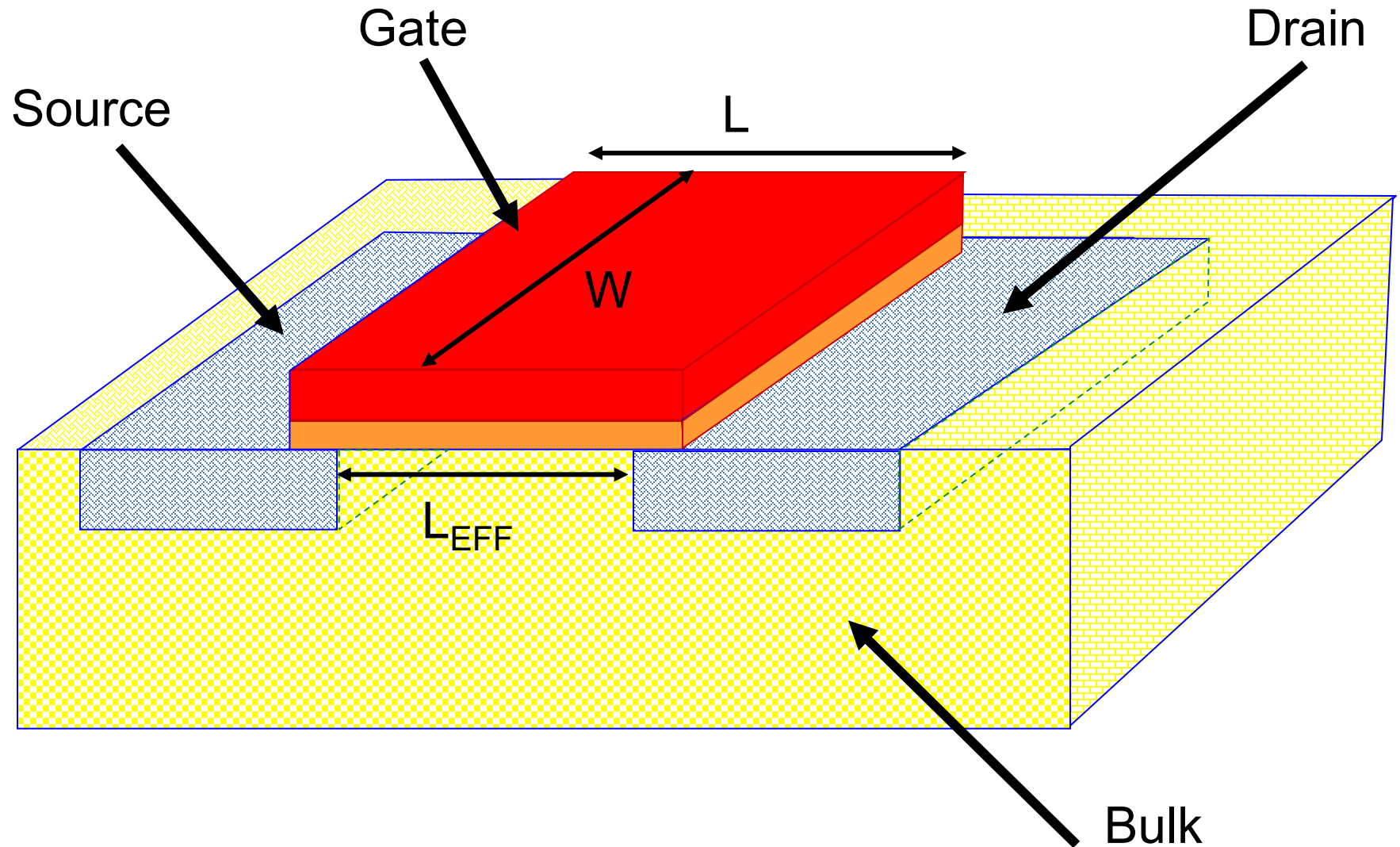


n-active

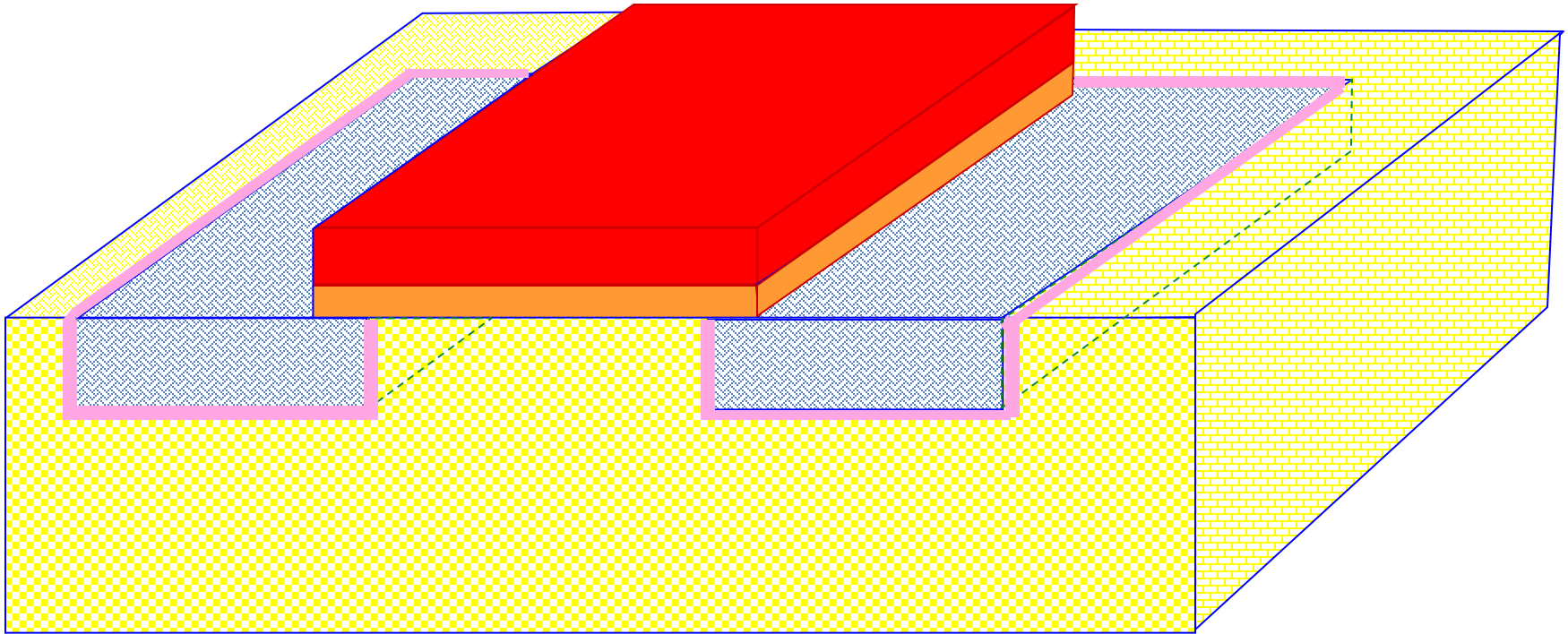




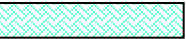


p-sub

# n-Channel MOSFET



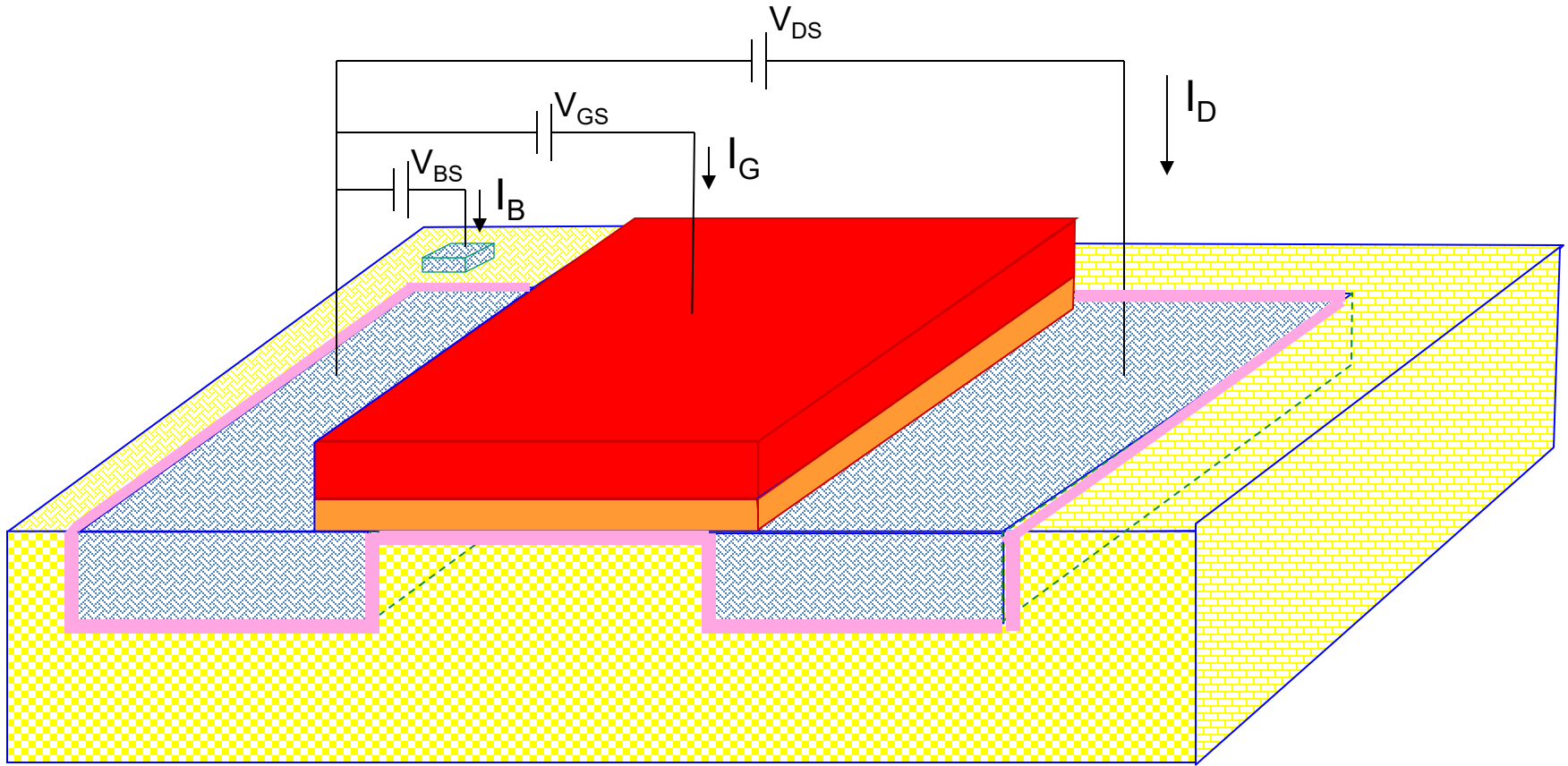
# n-Channel MOSFET



	Poly		Gate oxide
	n-active		p-sub
	depletion region (electrically induced)		

- In what follows assume all pn junctions reverse biased (almost always used this way)
- Extremely small reverse bias pn junction current can be neglected in most applications

# n-Channel MOSFET Operation and Model



Apply small  $V_{GS}$

( $V_{DS}$  and  $V_{BS}$  assumed to be small)

Depletion region electrically induced in channel

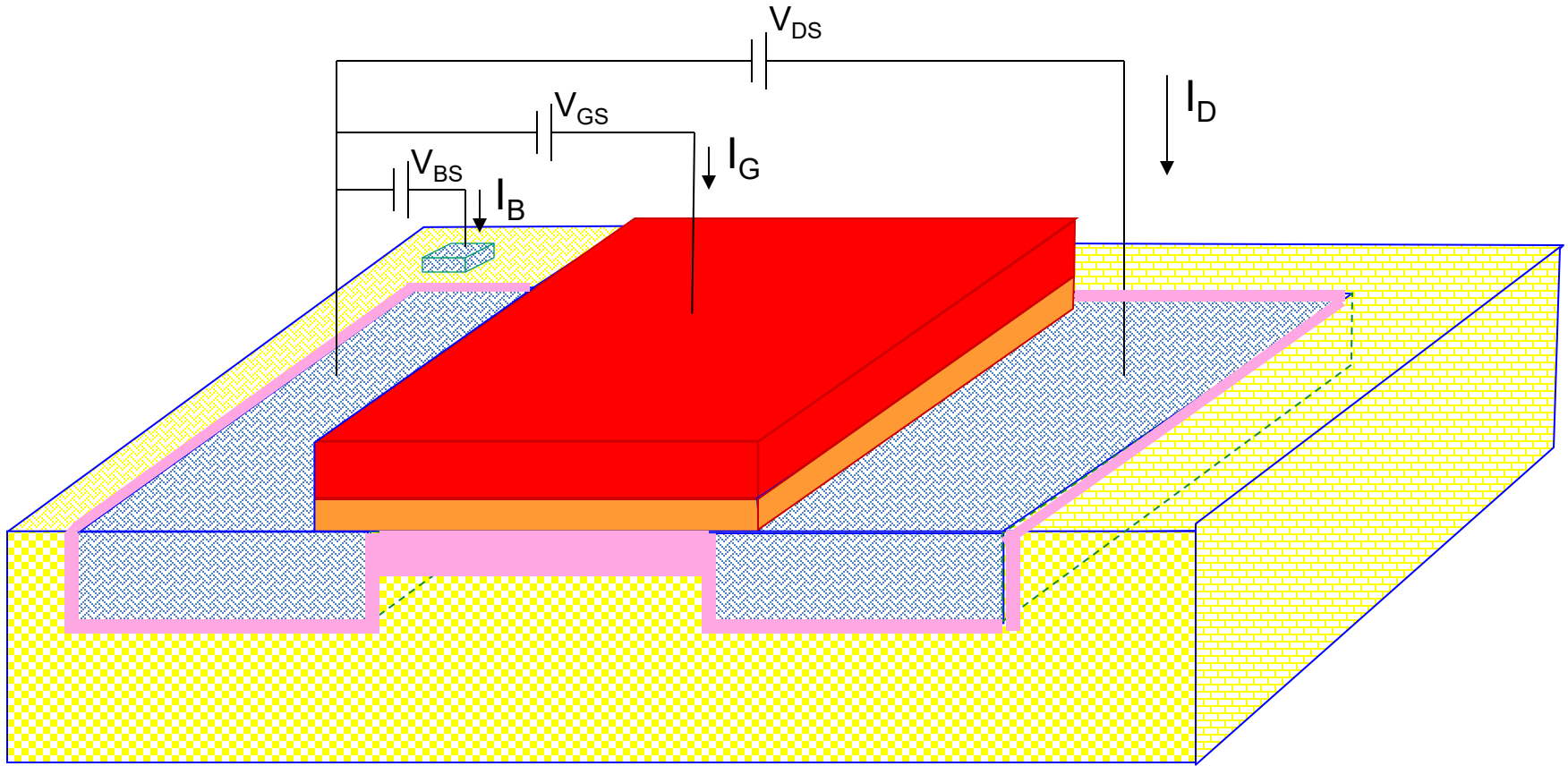
Termed “cutoff” region of operation

$$I_D=0$$

$$I_G=0$$

$$I_B=0$$

# n-Channel MOSFET Operation and Model

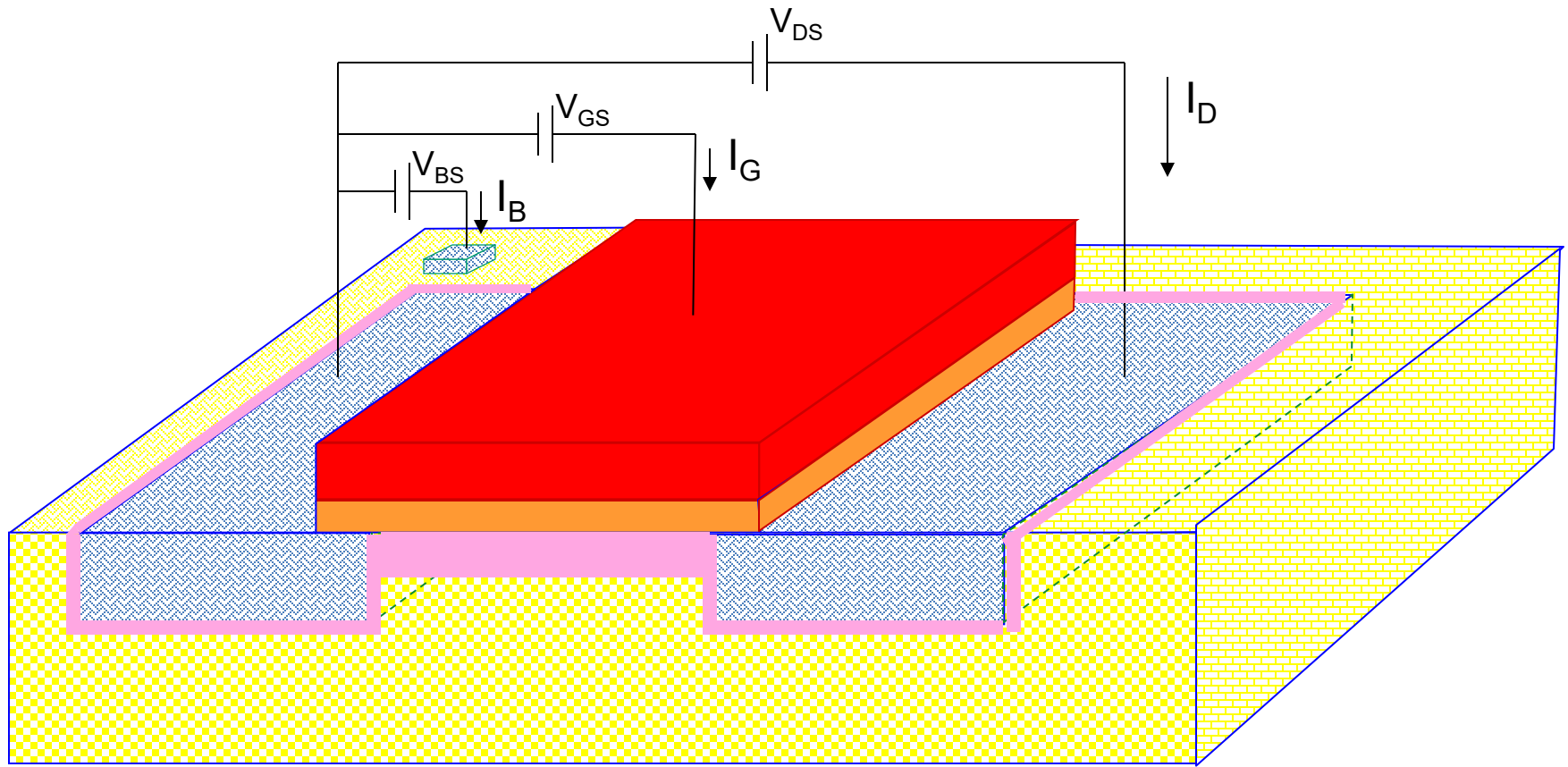


Increase  $V_{GS}$   
( $V_{DS}$  and  $V_{BS}$  assumed to be small)

Depletion region in channel becomes larger

$$\begin{aligned} I_D &= 0 \\ I_G &= 0 \\ I_B &= 0 \end{aligned}$$

# n-Channel MOSFET Operation and Model



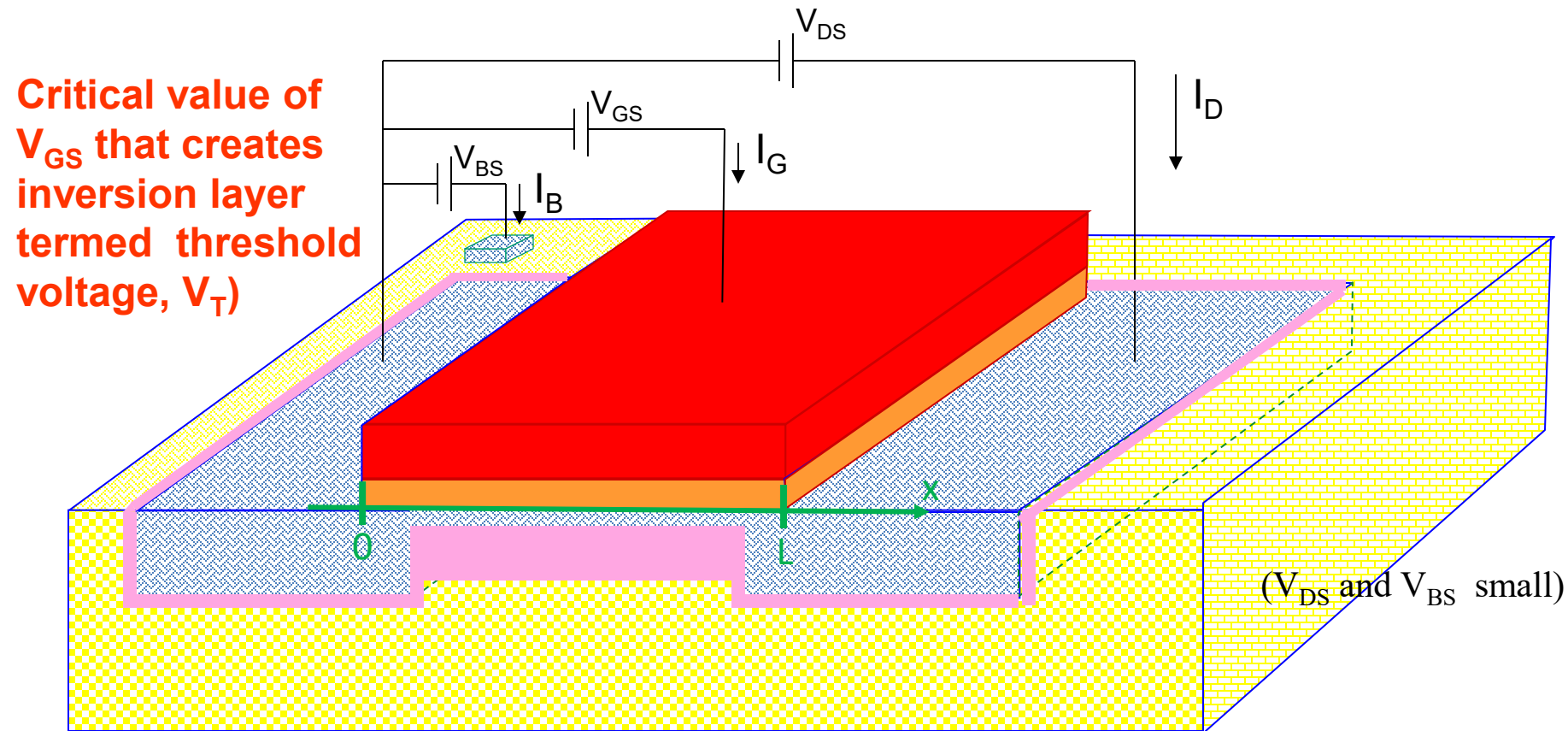
$$I_D=0$$

$$I_G=0$$

$$I_B=0$$

Model in Cutoff Region

# n-Channel MOSFET Operation and Model



Increase  $V_{GS}$  more

Inversion layer forms in channel

Inversion layer will support current flow from D to S

Channel behaves as thin-film resistor

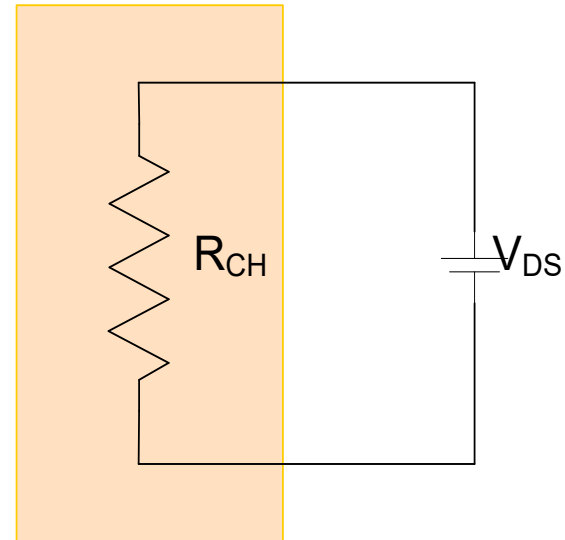
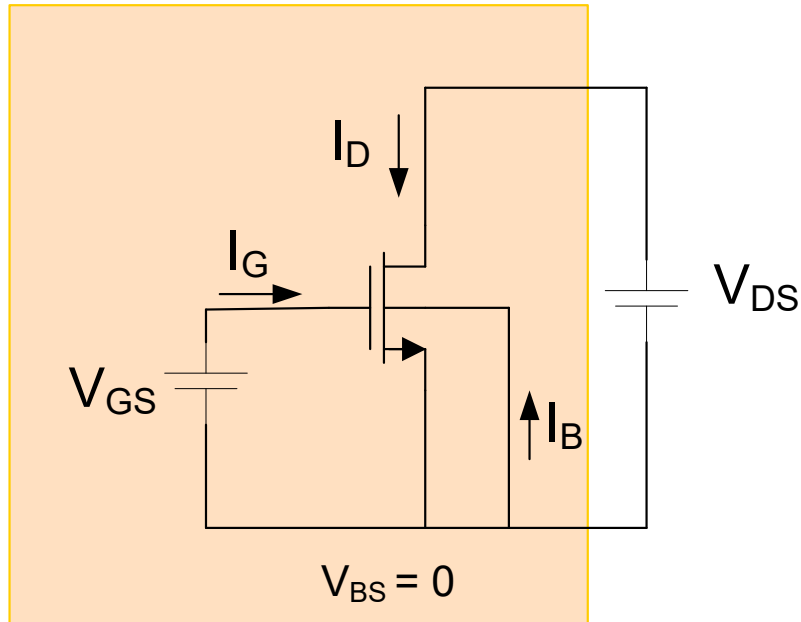
$$I_D R_{CH} = V_{DS}$$

$$I_G = 0$$

$$I_B = 0$$



# Triode Region of Operation



For  $V_{DS}$  small

$$R_{CH} = \frac{L}{W} \frac{1}{(V_{GS} - V_{TH}) \mu C_{OX}}$$

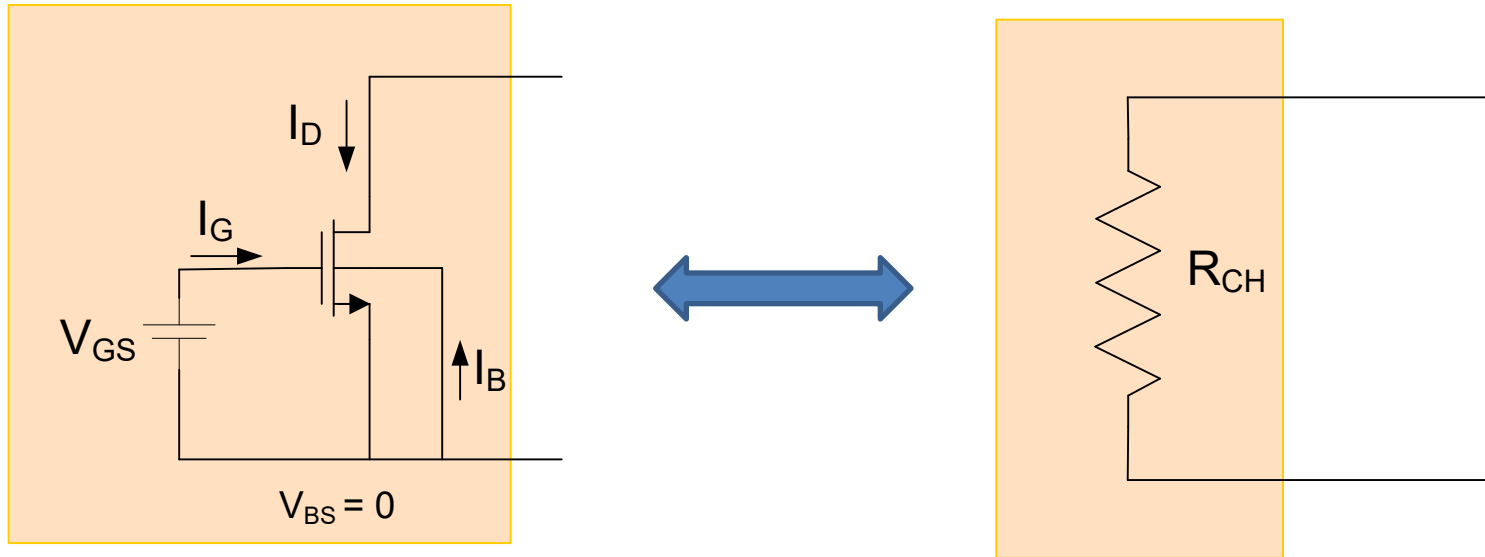
$$I_D = \mu C_{OX} \frac{W}{L} (V_{GS} - V_{TH}) V_{DS}$$

$$I_G = I_B = 0$$

Behaves as a resistor between drain and source

Model in Deep Triode Region

# Triode Region of Operation

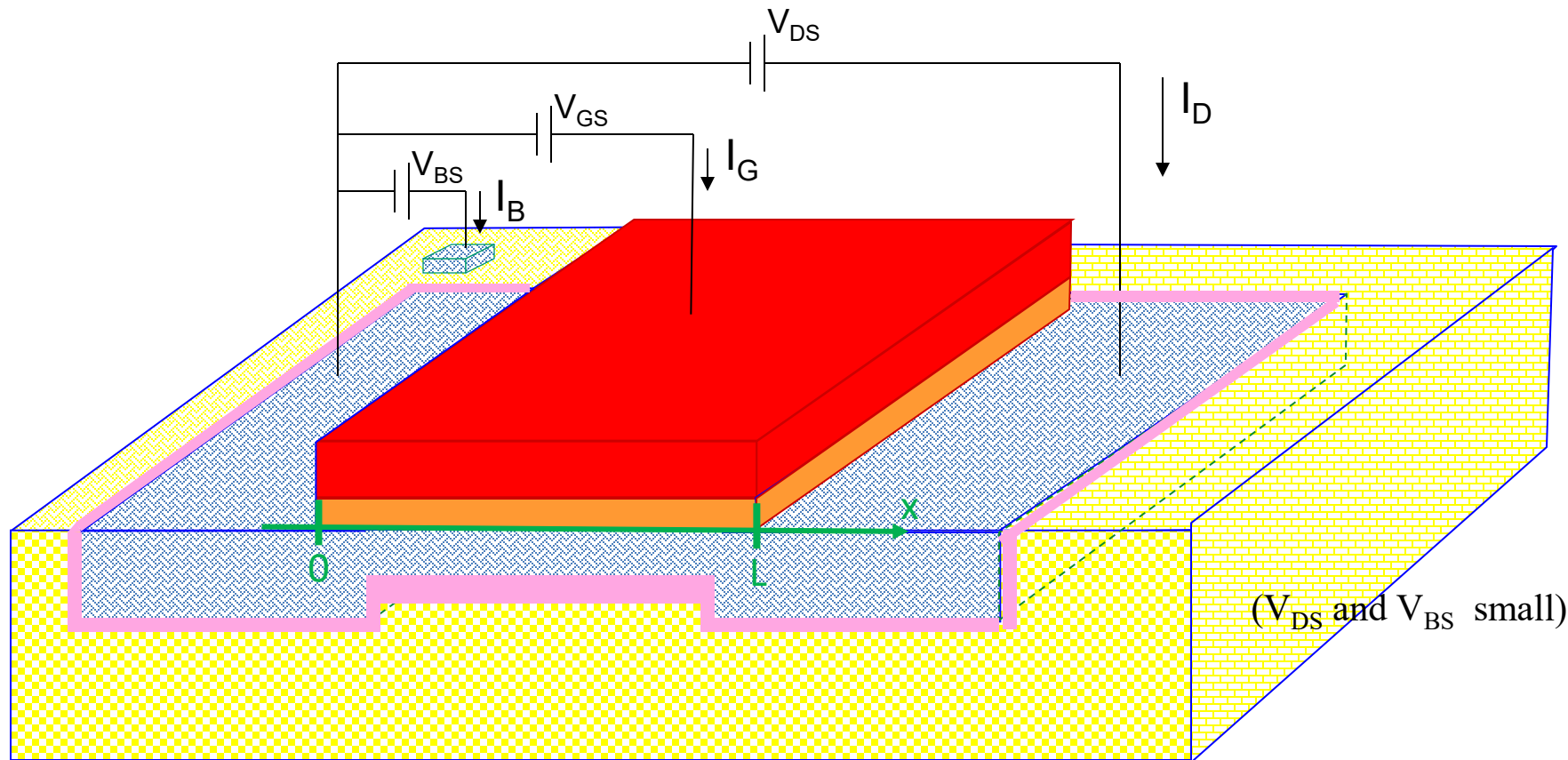


For  $V_{DS}$  small

$$R_{CH} = \frac{L}{W} \frac{1}{(V_{GS} - V_{TH}) \mu C_{OX}}$$

Resistor is controlled by the voltage  $V_{GS}$   
Termed a "Voltage Controlled Resistor" (VCR)

# n-Channel MOSFET Operation and Model



Increase  $V_{GS}$  more (with  $V_{DS}$  and  $V_{BS}$  still small)

$V_{GC}(x)$  approx. constant for small  $V_{DS}$

Inversion layer in channel thickens

$R_{CH}$  will decrease

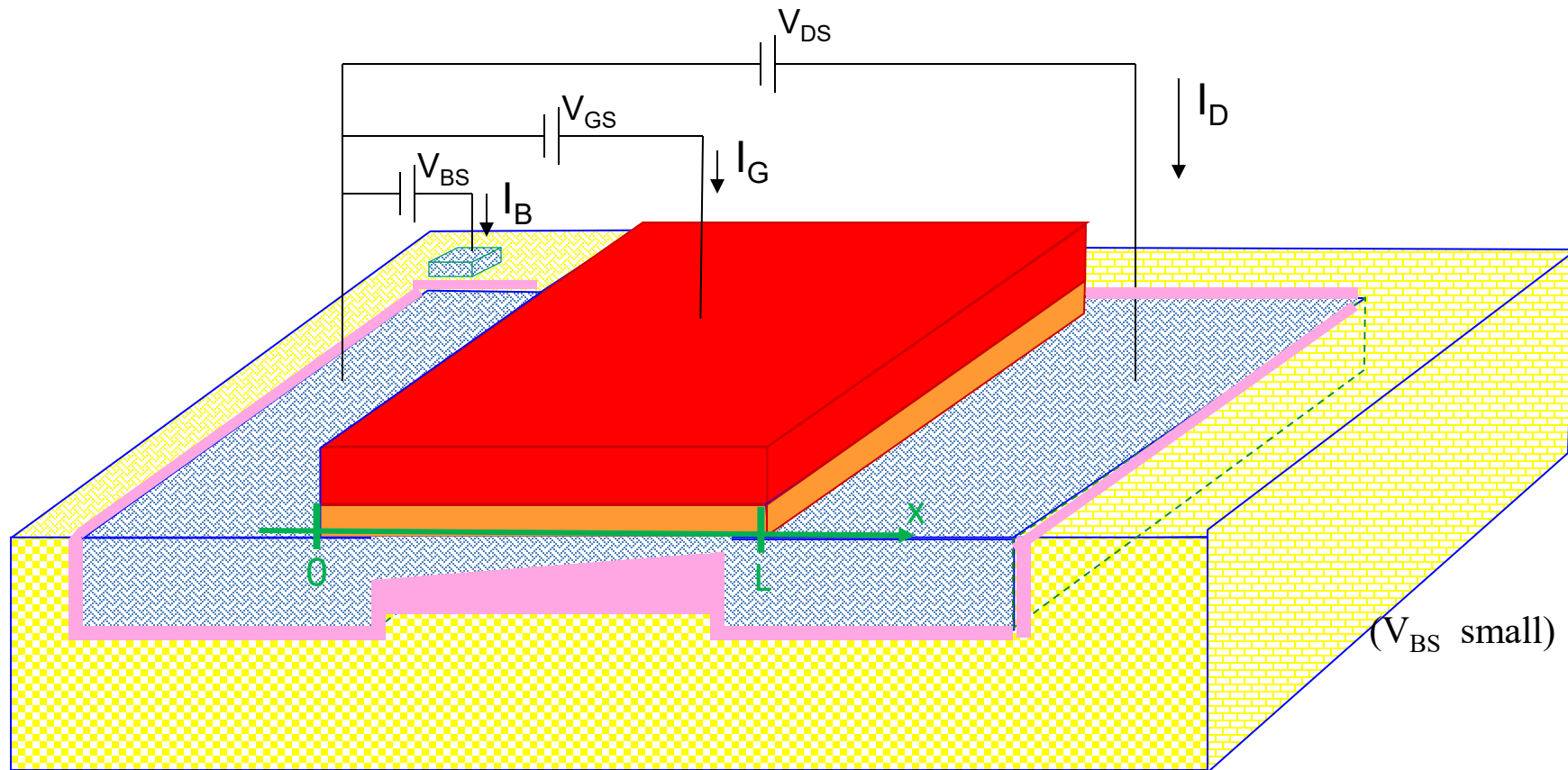
Termed “ohmic” or “triode” region of operation

$$I_D R_{CH} = V_{DS}$$

$$I_G = 0$$

$$I_B = 0$$

# n-Channel MOSFET Operation and Model



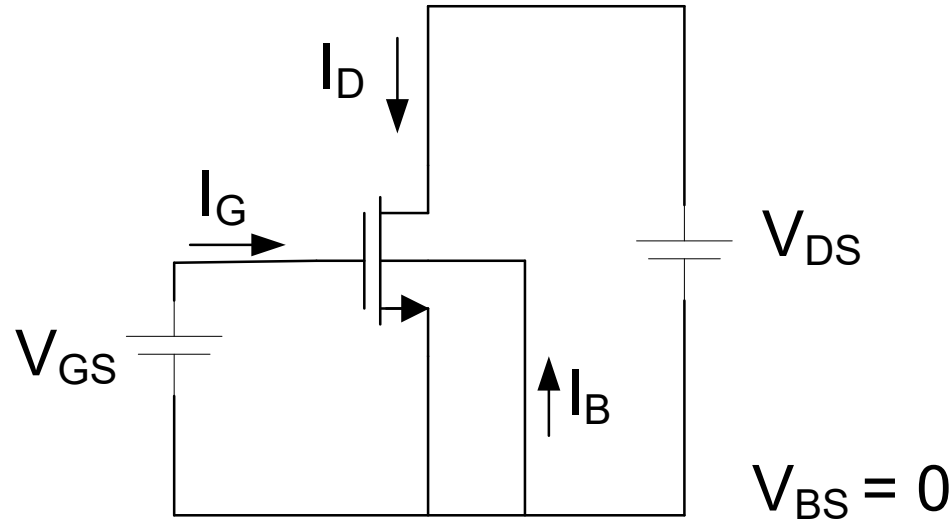
Increase  $V_{DS}$

$V_{GC}(x)$  changes with  $x$  for larger  $V_{DS}$

Inversion layer thins near drain  
 $I_D$  no longer linearly dependent upon  $V_{DS}$   
 Still termed “ohmic” or “triode” region of operation

$$\begin{aligned} I_D &=? \\ I_G &=0 \\ I_B &=0 \end{aligned}$$

# Triode Region of Operation



For  $V_{DS}$  larger

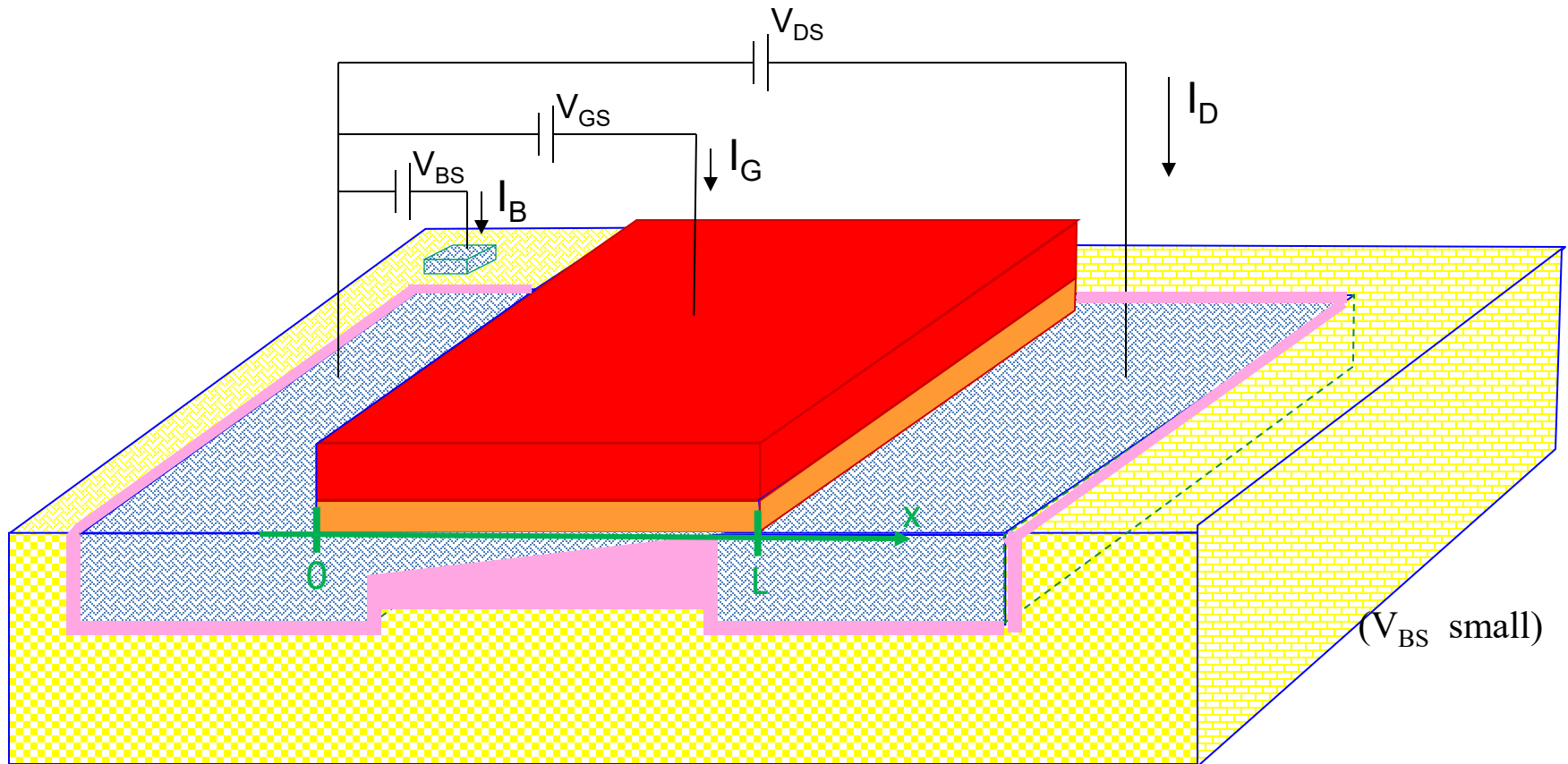
~~$$R_{CH} = \frac{L}{W} \frac{1}{(V_{GS} - V_{TH}) \mu C_{OX}}$$~~

$$I_D = \mu C_{OX} \frac{W}{L} \left( V_{GS} - V_{TH} - \frac{V_{DS}}{2} \right) V_{DS}$$

$$I_G = I_B = 0$$

Model in Triode Region

# n-Channel MOSFET Operation and Model



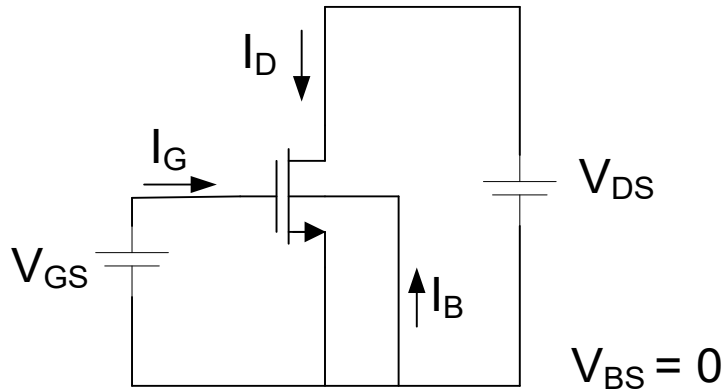
Increase  $V_{DS}$  even more

$V_{GC}(L) = V_{TH}$  when channel saturates

Inversion layer disappears near drain  
 Termed “saturation” region of operation  
 Saturation first occurs when  $V_{DS} = V_{GS} - V_{TH}$

$I_D = ?$   
 $I_G = 0$   
 $I_B = 0$

# Saturation Region of Operation



For  $V_{DS}$  at onset of saturation

$$I_D = \mu C_{OX} \frac{W}{L} \left( V_{GS} - V_{TH} - \frac{V_{DS}}{2} \right) V_{DS}$$

*or equivalently*

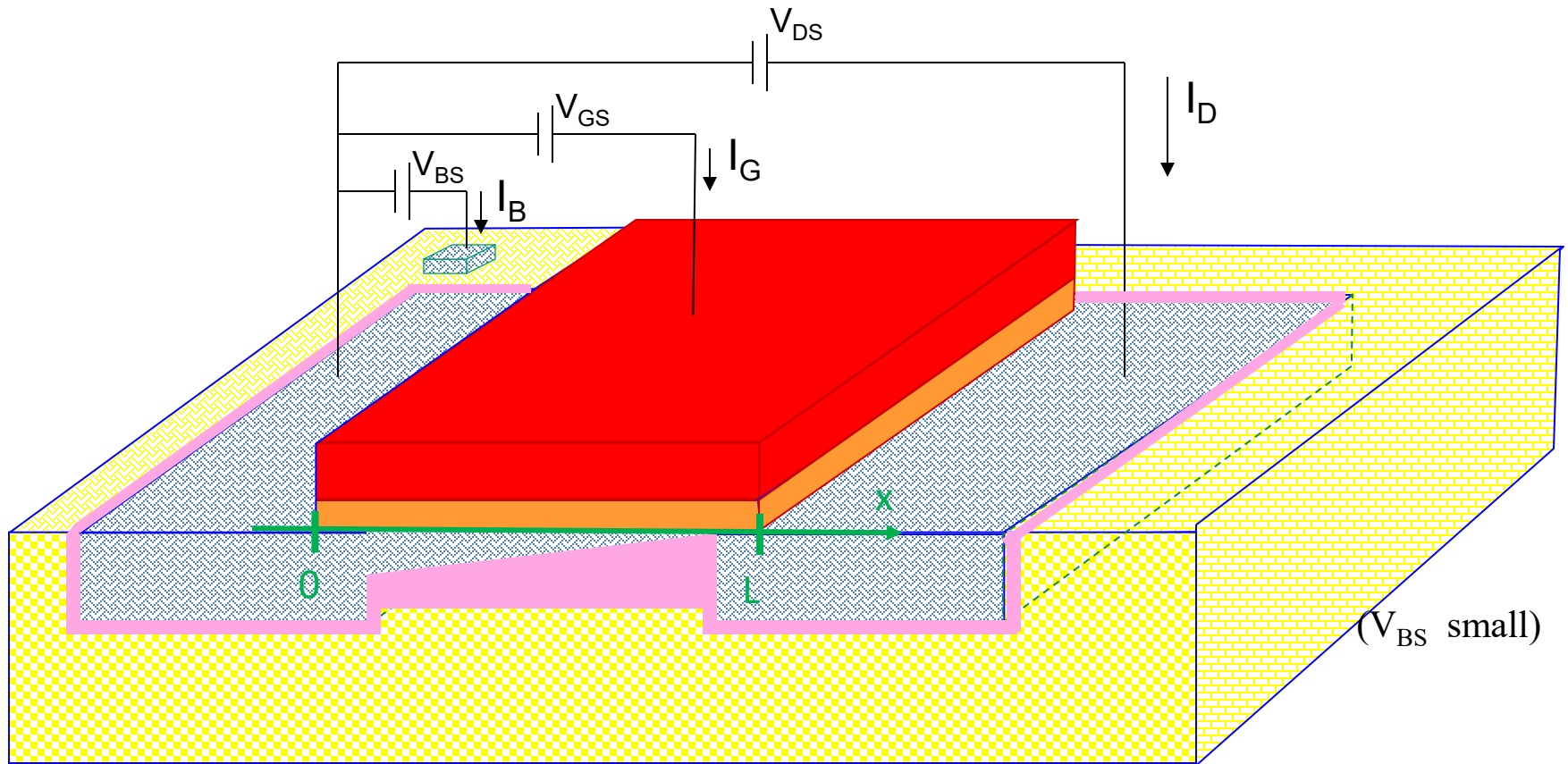
$$I_D = \mu C_{OX} \frac{W}{L} \left( V_{GS} - V_{TH} - \frac{V_{GS} - V_{TH}}{2} \right) (V_{GS} - V_{TH})$$

*or equivalently*

$$I_D = \frac{\mu C_{OX} W}{2L} (V_{GS} - V_{TH})^2$$

$$I_G = I_B = 0$$

# n-Channel MOSFET Operation and Model



Increase  $V_{DS}$  even more (beyond  $V_{GS} - V_{TH}$ )

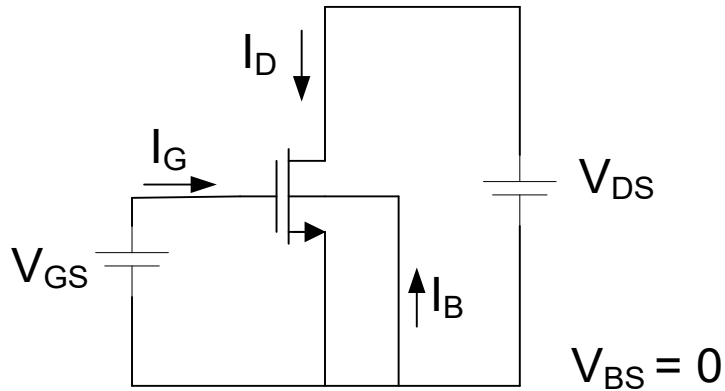
Nothing much changes !!

Termed “saturation” region of operation

$$\begin{aligned} I_D &=? \\ I_G &=0 \\ I_B &=0 \end{aligned}$$



# Saturation Region of Operation



For  $V_{DS}$  in Saturation

$$I_D = \frac{\mu C_{OX} W}{2L} (V_{GS} - V_{TH})^2$$

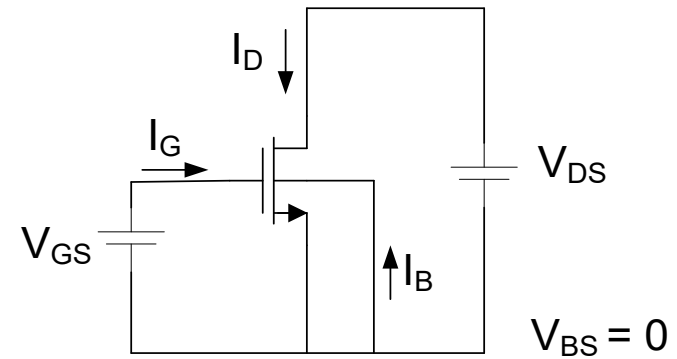
$$I_G = I_B = 0$$

Model in Saturation Region

# Model Summary

n-channel MOSFET

Notation change:  $V_T = V_{TH}$ , don't confuse  $V_T$  with  $V_t = kT/q$



$$I_D = \begin{cases} 0 & V_{GS} \leq V_{TH} \quad \text{Cutoff} \\ \mu C_{OX} \frac{W}{L} \left( V_{GS} - V_{TH} - \frac{V_{DS}}{2} \right) V_{DS} & V_{GS} \geq V_{TH} \quad V_{DS} < V_{GS} - V_{TH} \quad \text{Triode} \\ \mu C_{OX} \frac{W}{2L} (V_{GS} - V_{TH})^2 & V_{GS} \geq V_{TH} \quad V_{DS} \geq V_{GS} - V_{TH} \quad \text{Saturation} \end{cases}$$

$$I_G = I_B = 0$$

Model Parameters:  $\{\mu, V_{TH}, C_{OX}\}$  Design Parameters :  $\{W, L\}$

This is a piecewise model (not piecewise linear though)

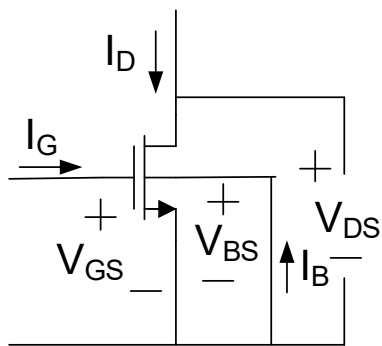
Piecewise model is continuous at transition between regions

(Deep triode special case of triode where  $V_{DS}$  is small  $R_{CH} = \frac{L}{W} \frac{1}{(V_{GS} - V_{TH}) \mu C_{OX}}$ )

**Note: This is the third model we have introduced for the MOSFET**

# Model Summary

n-channel MOSFET



$$I_D = \begin{cases} 0 & V_{GS} \leq V_{TH} \\ \mu C_{OX} \frac{W}{L} \left( V_{GS} - V_{TH} - \frac{V_{DS}}{2} \right) V_{DS} & V_{GS} \geq V_{TH} \quad V_{DS} < V_{GS} - V_{TH} \\ \mu C_{OX} \frac{W}{2L} (V_{GS} - V_{TH})^2 & V_{GS} \geq V_{TH} \quad V_{DS} \geq V_{GS} - V_{TH} \end{cases}$$

$I_G = I_B = 0$

Observations about this model (developed for  $V_{BS}=0$ ):

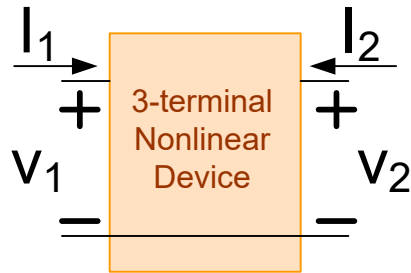
$$I_D = f_1(V_{GS}, V_{DS})$$

$$I_G = f_2(V_{GS}, V_{DS})$$

$$I_B = f_3(V_{GS}, V_{DS})$$

This is a nonlinear model characterized by the functions  $f_1$ ,  $f_2$ , and  $f_3$  where we have assumed that the port voltages  $V_{GS}$  and  $V_{DS}$  are the independent variables and the drain currents are the dependent variables

# General Nonlinear Models

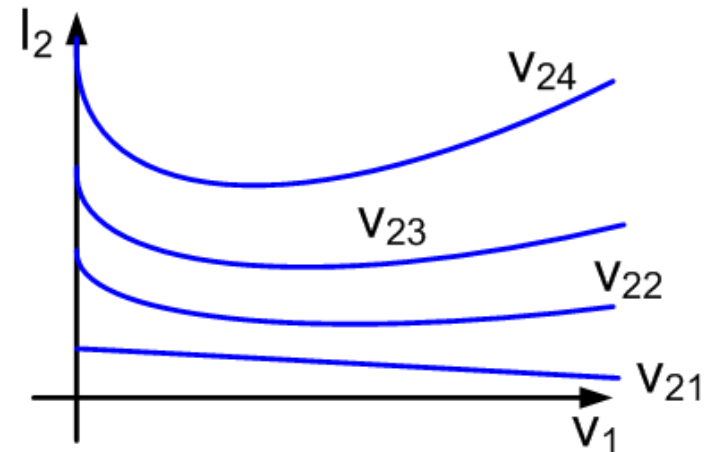
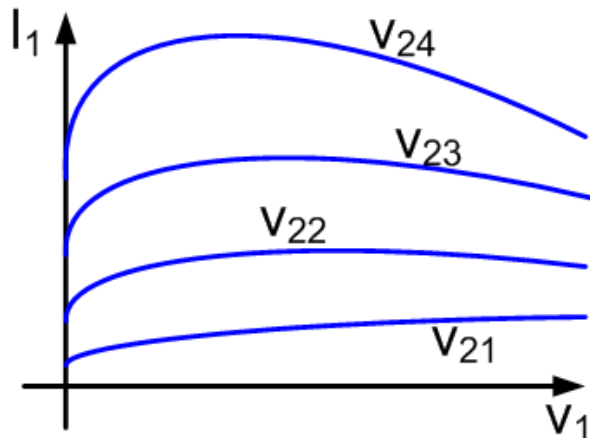


$$I_1 = f_1(V_1, V_2)$$

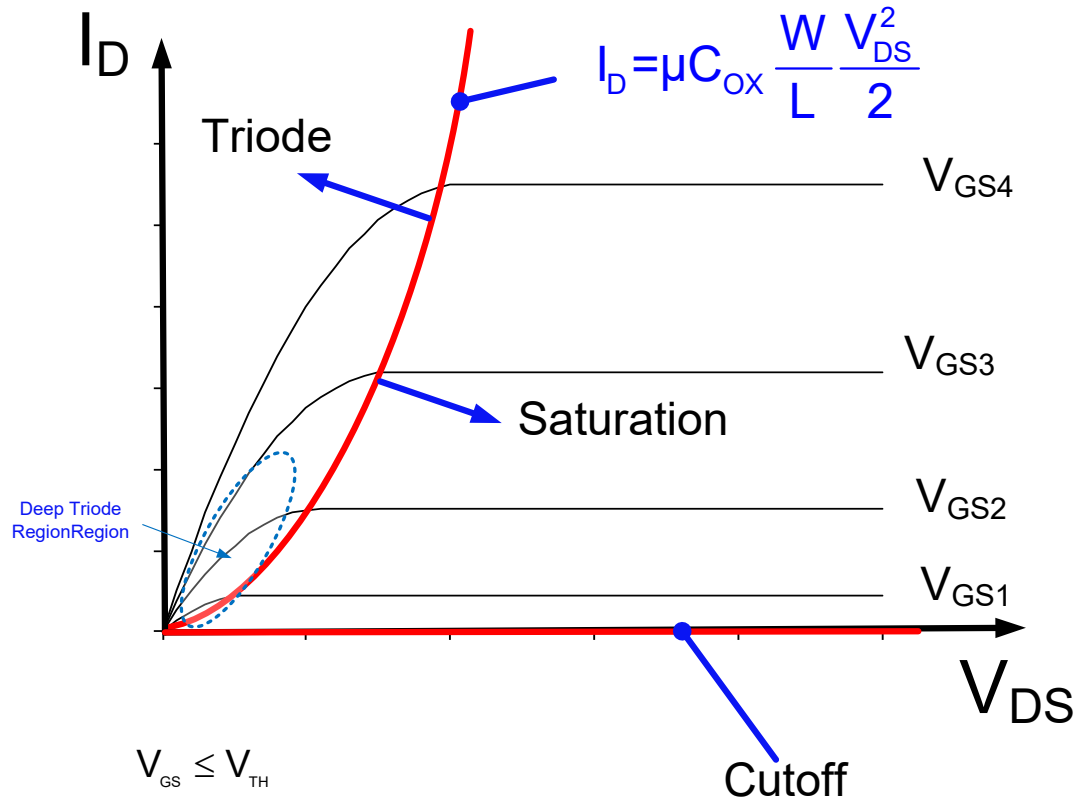
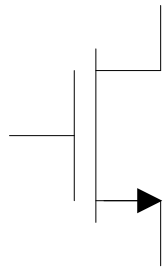
$$I_2 = f_2(V_1, V_2)$$

$I_1$  and  $I_2$  are 3-dimensional relationships which are often difficult to visualize

Two-dimensional representation of 3-dimensional relationships



# Graphical Representation of MOS Model

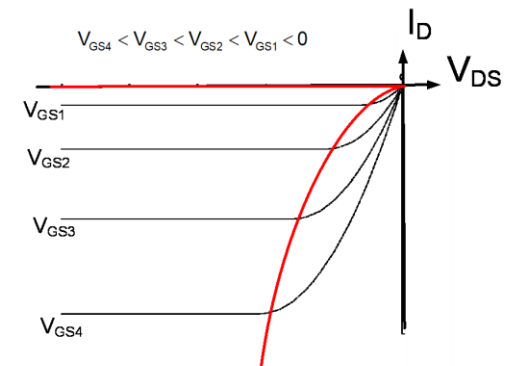
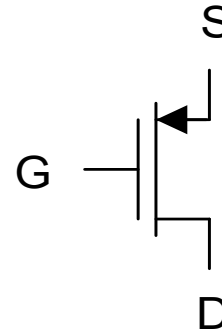
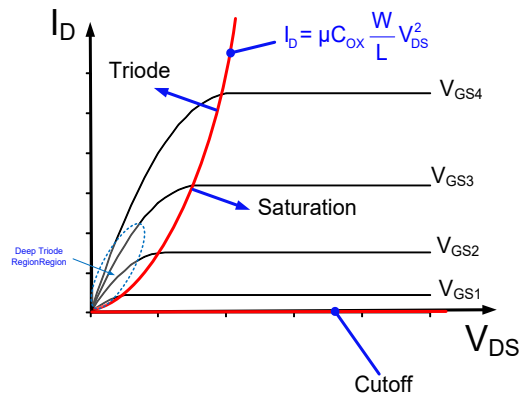
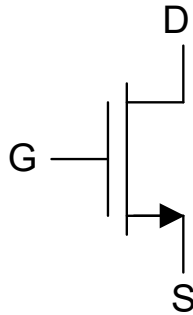


$$I_D = \begin{cases} 0 & V_{GS} \leq V_{TH} \\ \mu C_{ox} \frac{W}{L} \left( V_{GS} - V_{TH} - \frac{V_{DS}}{2} \right) V_{DS} & V_{GS} \geq V_{TH} \quad V_{DS} < V_{GS} - V_{TH} \\ \mu C_{ox} \frac{W}{2L} (V_{GS} - V_{TH})^2 & V_{GS} \geq V_{TH} \quad V_{DS} \geq V_{GS} - V_{TH} \end{cases}$$

$$I_G = I_B = 0$$

Parabola separated triode and saturation regions and corresponds to  $V_{DS} = V_{GS} - V_{TH}$

# PMOS and NMOS Models



- Functional form identical, sign changes and parameter values different
- Will give details about p-channel model later



Stay Safe and Stay Healthy !

End of Lecture 16